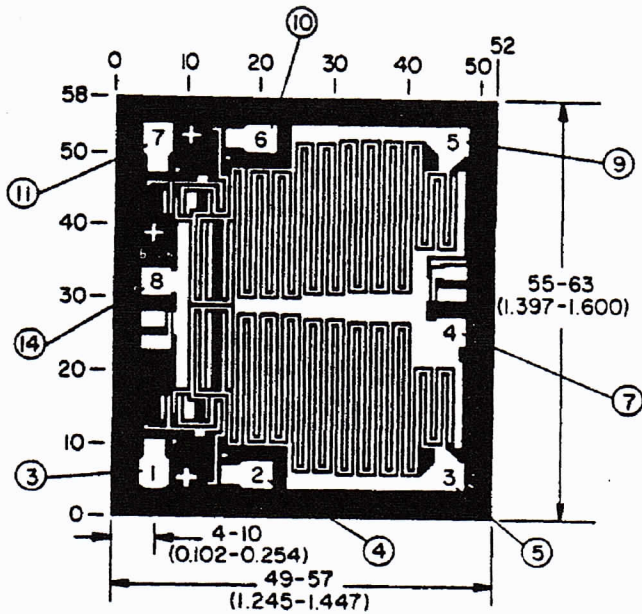




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD	FUNCTION
1	A
2	B
3	$C = \overline{A \cdot B}$
4	VSS
5	$F = \overline{D \cdot E}$
6	E
7	D
8	VDD

NOTE NOS. IN PADS FOR CD40107BE
 NOS. OUTSIDE CHIP FOR CD40107BF

Top Material: Al
Backside Material: Silicon
Bond Pad Size: .004" X .004" min.
Backside Potential:
Mask Ref:

APPROVED BY: DK

DIE SIZE .052 X .058"

DATE: 4/27/16

MFG: Harris (RCA)

THICKNESS .010"

P/N: CD40107B